

## Loctite® 3565 High performance epoxy, high Tg and low CTE High Tg Underfill

Category: Polymer, Adhesive, Thermoset

## **Material Notes:**

COB/DCA Encapsulants are essential to the reliability of flip chip assemblies because they minimize the thermal mismatch between the flip chip and substrate.Loctite® Underfills and Encapsulants improve assembly operations by providing superior reliability and faster throughput. Improved reliability is achieved through products that have a high Tg, low CTE, high throughput and excellent adhesion. Faster throughput and higher yields are achieved through faster flow characteristics and increased cure speeds.Loctite® 3565 High performance epoxy, high Tg and low CTE High Tg UnderfillA high performance underfill for flip chip devices. Specifically formatted for high reliability, hybrid and MCM applications. Designed for gaps down to 1 mil.

## Order this product through the following link:

http://www.lookpolymers.com/polymer\_Loctite-3565-High-performance-epoxy-high-Tg-and-low-CTEHigh-Tg-Underfill.php

Physical Properties	Metric	English	Comments
Density	1.74 g/cc	0.0629 lb/in <sup>3</sup>	
Viscosity	45000 cP	45000 cP	Haake cone and plate rheometer @ 5/sec (35mm/2° cone)

Mechanical Properties	Metric	English	Comments
Tensile Modulus	3.45 GPa	500 ksi	

Thermal Properties	Metric	English	Comments
CTE, linear	25.0 μm/m-°C	13.9 μin/in-°F	
GTL, IIIIeai	@Temperature 20.0 °C	@Temperature 68.0 °F	
Glass Transition Temp, Tg	155 °C	311 °F	

Processing Properties	Metric	English	Comments	
Cure Time	30.0 min	0.500 hour	Full Cure	
Cure Time	@Temperature 150 °C	@Temperature 302 °F	ruii Guie	
Shelf Life	3.00 Month	3.00 Month		
Shell Life	@Temperature -40.0 °C	@Temperature -40.0 °F		

## **Contact Songhan Plastic Technology Co.,Ltd.**

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